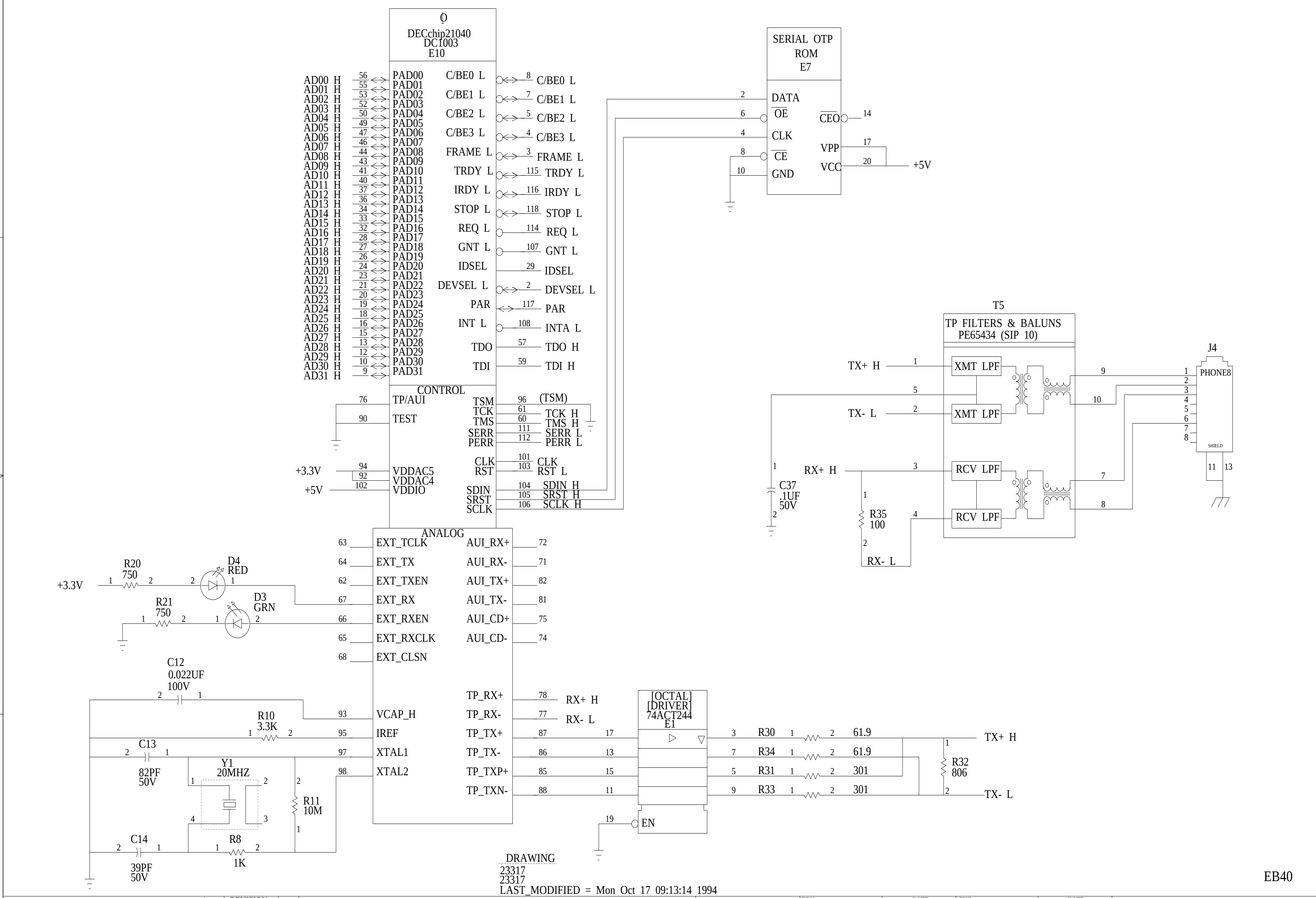


REVISION		
CHK	CHANGE NO.	REV
	5423317-MK101 J. PATEL RZ. BUREAU	B

EC-QECAA-TE

digital

DRN.	DATE	ENG.	DATE
J. PATEL	04-FEB-94	YUVAL BACHAR	04-FEB-94
CHK'D. J. PATEL	04-FEB-94	BOARD LOCATION:	

SHEET 1 OF 3

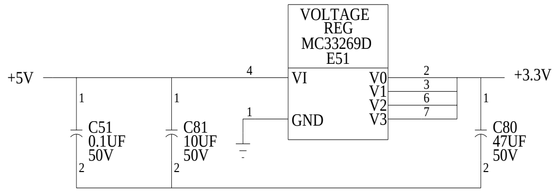
USRA:

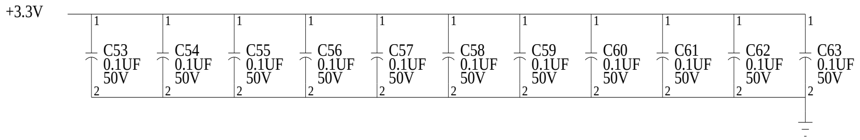
FIRST USED ON OPTION/MODEL:

TOP DOCUMENT NUMBER: K-DD-5423317-0-0

TITLE: 21040 PCI EVAL BOARD

SIZE	CODE	NUMBER	REV.
B	CS	5423317-0-1	B

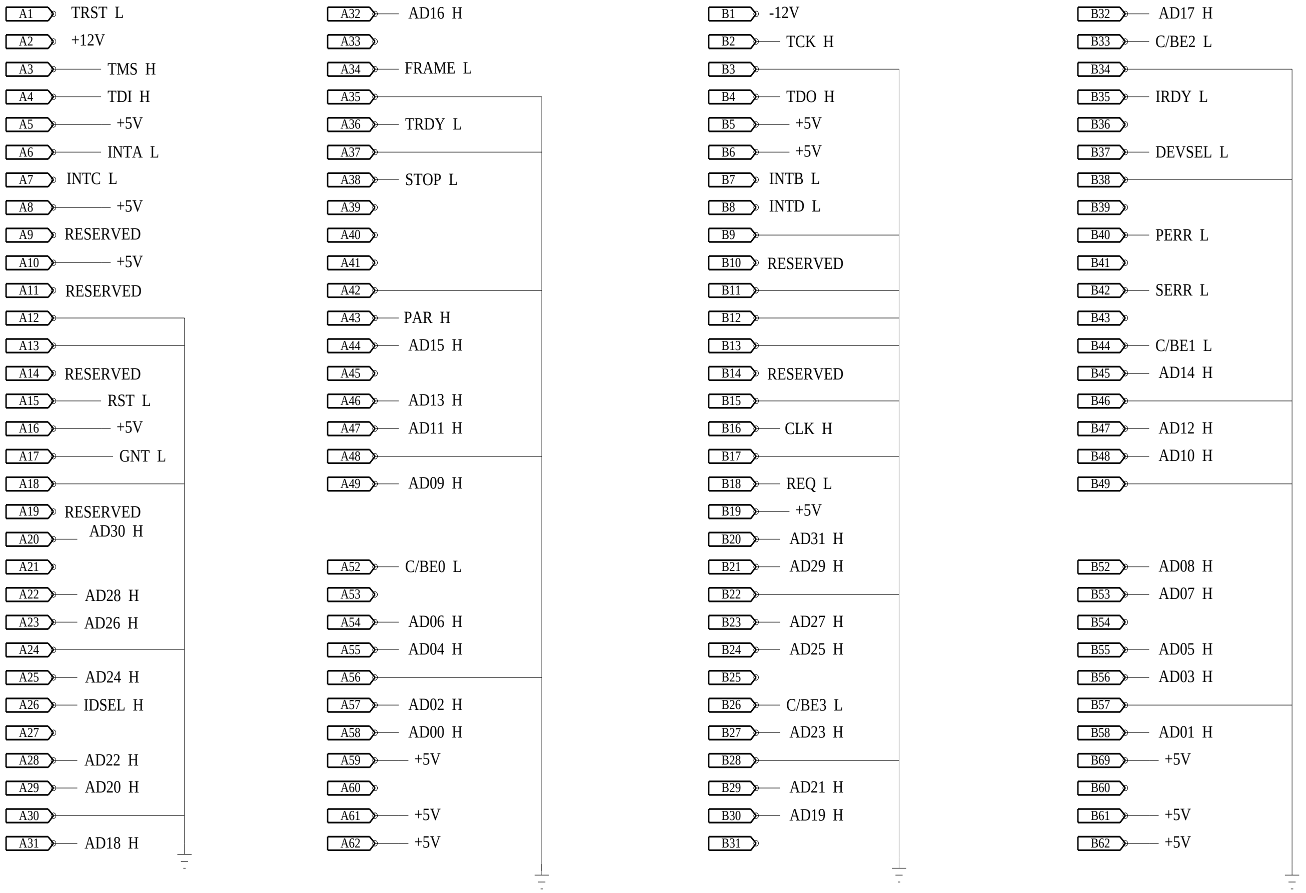




EB40

ENG. YUVAL BACHAR	DATE 04-FEB-94	TITLE: 21040 PCI EVAL BOARD		
BOARD LOCATION:				
SHEET 2 OF 3				
TOP DOCUMENT NUMBER: K-DD-5423317-0-0		SIZE B	CODE CS	NUMBER 5423317-0-1	REV. B

DRAWING
LAST_MODIFIED = Fri Jul 8 12:35:39 1994



PCI FINGERS

EB40

ENG. YUVAL BACHAR	DATE 04-FEB-94
BOARD LOCATION:	
SHEET 3 OF 3	
TOP DOCUMENT NUMBER: K-DD-5423317-0-0	
TITLE: 21040 PCI EVAL BOARD	
SIZE B	CODE CS
NUMBER 5423317-0-1	REV. B

DRAWING
LAST_MODIFIED = Tue Oct 11 13:29:45 1994

DATE	RESPONSIBLE ENGINEER	ECO NUMBER	REV

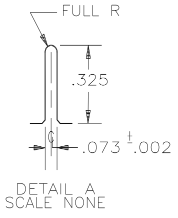
PRINTED WIRE BOARD LAYER CONSTRUCTION

LAYER	DIELECTRIC SPACING	LAYER TYPE	COPPER WEIGHT	LINE WIDTH(S)
1		SIGNAL	0,5 OZ + PLATING	0.008''
	0.018''+/--.003''			
2		PLANE	1.0 OZ	
	0.020'' REFERNCE			
3		PLANE	1.0 OZ	
	0.018''+/-.003''			
4		SIGNAL	0,5 OZ + PLATING	0.008''

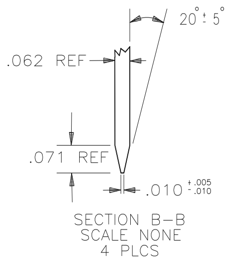
OVERALL THICKNESS SPECIFICATION = 0.062+/- .007(PLATING TO PLATING)
1.0 OZ. COPPER FOIL THICKNESS IS 0.0010 MINIMUM AFTER PROCESSING
0.5OZ. COPPER FOIL THICKNESS IS 0.003 MINIMUM AFTER PROCESSING
OUTER LAYERS ARE STARTED WITH 0.5 OZ. COPPER AND PLATED TO 0.0014 MINIMUM COPPER THICKNESS.
SIGNAL LINE WIDTH TOLERANCE = 0.008+/-0.0015
MINIMUM COPPER REQUIREMENT FOR PLATED THRU HOLE WALLS IS 0.0008

NOTES:

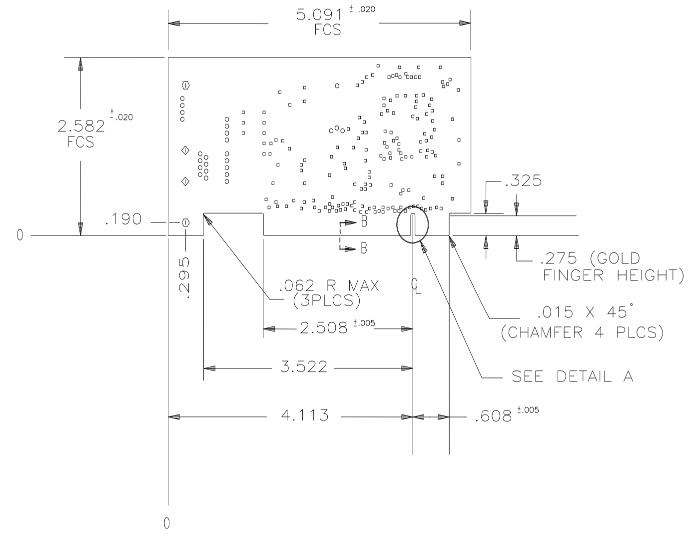
1. IF A CONFLICT BETWEEN THIS DOCUMENTATION/DESIGN PACKAGE AND ANY OTHER REFERENCED DOCUMENT EXISTS, THIS DOCUMENT /DESIGN PACKAGE WILL TAKE PRECEDENCE.
2. ALL ARTWORK FEATURES (IN ALL FORMATS) ARE SUPPLIED AT NOMIMAL DIMENSIONS. UNLESS OTHERWISE SPECIFIED, THE FINISHED CIRCUIT SHOULD REFLECT THESE DIMENSIONS INCLUDING ALLOWABLE FABRICATION TOLERANCES PER DIGITAL STANDARD 176. SOLDERMASK ARTWORK FEATURES ARE SUPPLIED AT ZERO CLEARENCE TO ASSOCIATED ETCH FEATURES WHICH REFLECT DESIRED COVERAGE. ALL ARTWORK AND DRILL FEATURES MAY BE MODIFIED TO ACCOMMODATE SPECIFIC FABRICATION PROCESSES.
3. ALL COPPER FOIL SHALL MEET OR EXCEED ANSI/IPC CF-150 TYPE ED (ELECTEODEPOSITED) CLASS 1 REQUIREMENTS.
4. DIELECTRIC MATERIAL TO BE FR4 WITH A MINIMUM GLASS TRANSITION TEMPERATURE OF 125 C.
5. NICKEL AND GOLD PLATE FINGER SET AREA PER DIGITAL STANDARD 176. VENDOR TO ADD PLATING BUSS BAR AND FINGER EXTENSION DETAIL FOR EACH CIRCUIT.
6. LIQUID PHOTOIMAGABLE SOLDERMASK (LPISM) IS REQUIRED ON BOTH SIDES OF THE PWB. NO SOLDERMASK WILL BE PER- MITTED ON THE TOP (SOLDERABLE SURFACE) OF ANY SURFACE MOUNT DEVICE PADS.



DETAIL A
SCALE NONE



SECTION B-B
SCALE NONE
4 PLCS



HOLE DATA (FOR STANDARD HOLE TOLERANCES USE DEC STD 176)				
SYMBOL	▫	○	◎	◈
FINISHED HOLE SIZE (INCHES)	.020	.032	.125	.128
POSITIVE TOLERANCE (INCHES)				
NEGATIVE TOLERANCE (INCHES)				
FINISHED HOLE SIZE (mm)				
POSITIVE TOLERANCE (mm)				
NEGATIVE TOLERANCE (mm)				
PLATED	Y	Y	N	N
QUANTITY	171	25	2	2

FROM LAYER 1 TO LAYER 4

FABRICATION INFORMATION — MATERIAL AND WORKMANSHIP FOR ALL FABRICATED PRINTED WIRING BOARDS MUST MEET THE REQUIREMENTS OF DEC STD 176

FABRICATE BOARD PER: AS SHOWN X STEP AND REPEAT CODE: NONE PRESS FIT COMPONENTS: YES NO X

DESIGN INFORMATION

NUMBER OF LAYERS: 4 LAYER CONSTRUCTION: AS SHOWN X
CONTROLLED IMPEDANCE: YES NO X CONTROLLED CAPACITANCE: YES NO X
SURFACE MOUNT TECH / MINIMUM PITCH: SIDE 1 .050 SIDE 2 N/A
PLANAR RESISTOR TECHNOLOGY: YES NO X NUMBER OF PRT LAYERS
BOARD FINISH: REFLOW TIN LEAD HASL X ALL COPPER OTHER
SOLDERMASK: NONE SIDE 1 X SIDE 2 X SMOBC: YES X NO
NOMENCLATURE: NONE SIDE 1 X SIDE 2 TENTED VIAS: YES NO X
MINIMUM VIA HOLE SIZE: .020 MINIMUM COMPONENT HOLE SIZE: .032
PAD EXPANSION: OUTER LAYERS X SIGNAL INNER LAYERS NONE
INCIRCUIT THIEVING: NONE SIDE 1 X SIDE 2 X AS SHOWN
TECHNOLOGY (LW/LS): LINE .008 SPACE .008
CIRCUIT OUTLINE/FINGER DETAIL: AS SHOWN X
SPECIAL REQUIREMENTS:

TOLERANCES

INCHES UNLESS OTHERWISE SPECIFIED

INCHES		mm		ANGLES
.XXX	± .010	.XX	± .25	±0 DEG
.XX	± .020	.X	± .50	30 MIN
.X	± .100	X.	± 2,50	

APPROVALS		DATE
DRAWN:	MIKE CICCONE	3-15-94
CHECKED:	STEVE CORCORAN	3-15-94
MECH ENG:		
PROJ ENG:		
MFG ENG:		

SCALE: 1:1
SHEET 1 OF 1
TOP DOC NO: K-DD-5023316-0-0

digital™

TITLE: CIRCUIT DRILL AND ETCH DRAWING

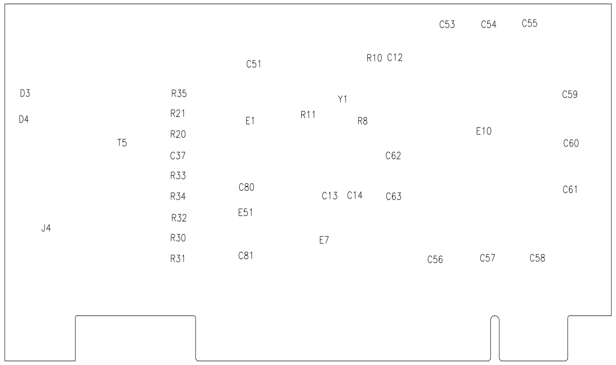
SIZE	CODE	NUMBER	REV
D	MD	5023316-0-0	AX00

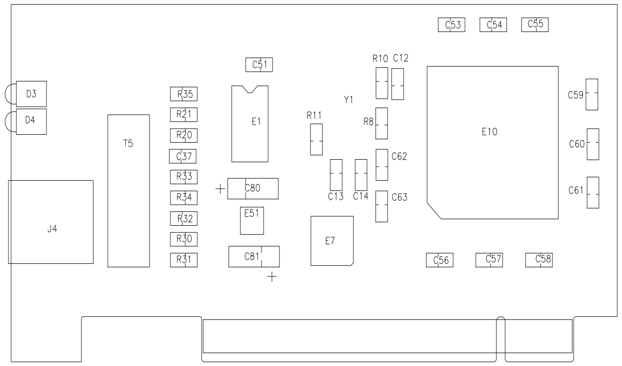
ETCH REV: A1 MEDIA K

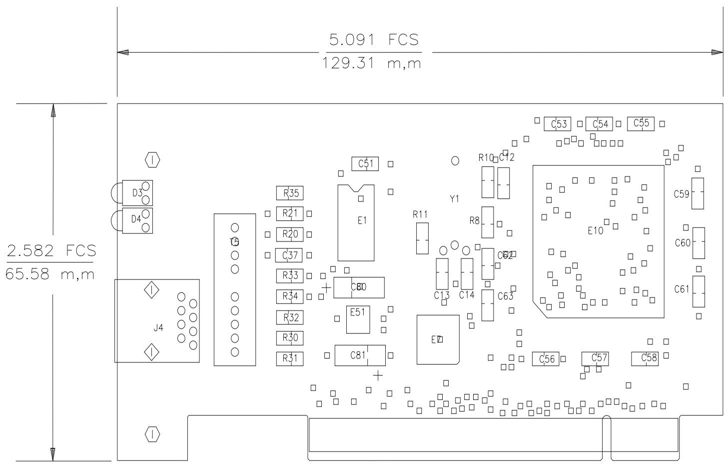
1 WO# 298203

SIZE	CODE	NUMBER	REV
D	UA	5423317-0-0	AX00

COMPONENT SIDE VIEW







DATE	RESPONSIBLE ENGINEER	ECO NO	REV

DATE	RESPONSIBLE ENGINEER	ECO NO	REV

NOTES:

DESIGN INFORMATION

SURFACE MOUNT TECHNOLOGY: SIDE 1 X SIDE 2 ___ NONE ___

APPROVALS		DATE
DRAWN:	MIKE CICCONE	3-15-94
CHECKED:	JIM CUNNINGHAM	3-24-94
MECH ENG:		
PROJ ENG:		
MFG ENG:		
SCALE:	2:1	
SHEET	1 OF 1	
TOP DOC NO:		

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TITLE: EB40 DECCHIP 21040

SIZE	CODE	NUMBER	REV
D	UA	5423317-0-0	AX00

ETCH REV A1 MEDIA K

WO# 298203